

# SMC (Strategic Materials Conference) Korea 2024

- 일정: 2024년 5월 29일(수)
- 장소: 경기도 수원컨벤션센터 3층 컨벤션홀2
- 주제: Materials Resilience: Navigating Challenges, Embracing Opportunities

시간	발표주제	연사
10:00-10:05	환영사	SEMI Korea
<b>Keynote</b>		
10:05-10:35	Process Technologies for Continuous Scaling of Logic Devices	Seongtae Oh, TEL
<b>Session 1: Market Trends</b>		
10:35-11:00	US-China Strategic Competition and Semiconductor Export Controls	Wonho Yeon, KIEP
11:00-11:25	Localization Challenges of the Materials Supply Chain	Mark Thirsk, Linx Consulting
11:25-11:50	Material Trends in Advanced Packaging & Power Module Packaging	Stefan CHITORAGA, Yole Group
11:50-13:00	Lunch	
<b>Session 2: Advanced Materials</b>		
13:00-13:25	Materials Innovation Advancing the Angstrom Era	Montray C. Leavy, Entegris
13:25-13:50	Advanced Packaging Materials and Evaluation Platform at Resonac	Katoh Sadaaki, Resonac
13:50-14:15	Dry Resist for Holistic EUV Patterning	Seongjun Heo, Lam Research
14:15-14:30	Break	
<b>Session 3: Sustainability</b>		
14:30-14:55	Sustainability Challenges of the Semiconductor Industry	Yongsung Kim, SK hynix
14:55-15:20	Trends in Regulation of PFASs (per- and polyfluoroalkyl substances) and Technological Development Strategies	Eunho Sohn, KRICT
15:20-15:45	Sustainability Opportunities for A Diverse and Secure Fluorinated Material Supply Chain	Karl Kim, Syensqo
15:45-16:10	Safer and Sustainable by Design: Strategies and Demonstration of PFAS Reduction in Photolithography Materials	Jae Hwan Sim, DuPont
16:10-16:35	CORBION: PURASOLV® ELECT for a more Sustainable Semiconductor Manufacturing	Floris Buijzen, Corbion
16:35-16:50	Break	
<b>Session 4: Collaboration</b>		
16:50-17:20	Technology and Future of Semiconductor Packaging Materials	Ki-Il Moon, SK hynix
17:20-17:50	Big Challenges for Small Worlds	Sungjun Park, Samsung Electronics
17:50-18:30	Networking Reception	